

**ABSTRACT OF THE DISCLOSURE**

A failure analysis device and a failure analysis method which enable easily a specification of a position of a failure point which is obtained from a back side upon a wiring pattern image which is obtained from a front side is provided.

5        Part of a light (51a) which is irradiated upon a front surface of an analyzed wafer (100) is reflected from a metal wiring, and is taken as a first wiring pattern image which is a reflect image of the analyzed wafer (100) by the CCD (11). An infrared light component of the light (51a) which passes a gap between the metal wiring is taken as a second wiring pattern image which is a transmission image of the analyzed wafer (100)

10      by an infrared light detector (12). Besides, the infrared light detector (12) also takes a failure light emission image by a failure point.